

Tribocomp® PA66 LGF30 PTFE15 MoS0.5 polyamide 66

Tribocomp® PA66 LGF30 PTFE15% MoS0.5% is a 30% long glass fiber reinforced high-flow PA66 compound containing a PTFE/MoS2 package. It has

been specifically designed for friction and wear applications. It can be easily be processed on most injection molding machines.

General

Material Status	 Commercial: Active 			
Availability	 Africa & Middle East Asia Pacific Europe	Latin America North America		
Filler / Reinforcement	 Long Glass Fiber, 30% Filler by Weight 	• PTFE, 15% Filler by Weight		
Features	Abrasion ResistantHeat StabilizedHigh Flow	High FrictionHigh Temperature StrengthLow Shrinkage		
Uses	Automotive ApplicationsAutomotive Under the HoodEngineering Parts	GearsIndustrial ApplicationsPower/Other Tools		
RoHS Compliance	 RoHS Compliant 			
Appearance	 Natural Color 			
Forms	 Pellets 			
Processing Method	Compression Molding	 Injection Molding 		
Physical	Dry	Conditioned Unit	Test method	
Density	1.50	g/cm³	ISO 1183	
Molding Shrinkage - Flow	0.40	%	ISO 294-4	
Water Absorption (Equilibrium, 23°C, 50% RH)	1.4	%	ISO 62	
Mechanical	Dry	Conditioned Unit	Test method	
Tensile Modulus			ISO 527-1	
23°C	10900	8000 MPa		
90°C	6700	MPa		
Tensile Stress			ISO 527-2	
Yield, 23°C	200	140 MPa		
Yield, 90°C	125	MPa		
Tensile Strain (Break, 23°C)	2.7	2.8 %	ISO 527-2	
Flexural Modulus (23°C)	10600	MPa	ISO 178	
Flexural Stress (23°C)	285	MPa	ISO 178	
Coefficient of Friction			ASTM D3702	
Dynamic	0.23			
Static	0.18			

Mechanical	Dry	Conditioned	Unit	Test method	
Wear Factor	13.0			ASTM D3702	
Impact	Dry	Conditioned	Unit	Test method	
Charpy Notched Impact Strength (23°C)	23		kJ/m²	ISO 179	
Charpy Unnotched Impact Strength (23°C)	75		kJ/m²	ISO 179	
Thermal	Dry	Conditioned	Unit	Test method	
Deflection Temperature Under Load					
0.45 MPa, Unannealed	262		°C	ISO 75-2/B	
1.8 MPa, Unannealed	258		°C	ISO 75-2/A	
Thermal Conductivity	0.29		W/m/K	ISO 22007	
Coefficient of Linear Thermal Expansion	1.9E-5		cm/cm/°C	ISO 11359-2	
Electrical	Dry	Conditioned	Unit	Test method	
Electric Strength (2.00 mm)	35		kV/mm	IEC 60243-1	
Comparative Tracking Index	500		V	IEC 60112	
Surface Resistivity	1.0E+12		ohms/sq	ASTM D257	
Additional Information					
	e listed as Molding Shrin ^p . methods.	kage ISO 294-4, was	tested in a	iccordance	
Injection		Dry Unit			
Drying Temperature	80 to 100 °C				
Drying Time	4.0 hr				
Suggested Max Moisture	0.10 %				
Rear Temperature	290 to 300 °C				
Middle Temperature	300 °C				
Front Temperature	300 °C				
Nozzle Temperature	300 °C				
Processing (Melt) Temp	< 300 °C				
Mold Temperature	80 to 120 °C				

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Injection Notes

Pre-drying -- Since polyamides are hygroscopic materials as well as sensitive to moisture during processing, this product should always be pre-dried. At a humidity content above 0.1%, the material will begin to degrade. Recommended drying time is 4 hours at 100°C in dry-air dryer.

Processing temperatures -- Melt temperature should be kept below 300°C in order to prevent degradation. The exact setting depends from machine and mold design, but is usually within the range indicated in the Processing Information section of this TDS.

Mold temperature -- The mold temperature is a compromise between the optimum properties that can be obtained from high crystallization, and cycle time. This material can be processed at mold temperatures between 80°C and 140°C. Optimum surface quality requires a mold temperature above 120°C.

Regrind -- Regrind of highly filled thermoplastic materials, such as this material, should only be recycled with special care. The regrind content must never exceed 15%, and only regrind of optimum quality should be used. In any case, part properties should be checked.

Notes

Typical properties: these are not to be construed as specifications.

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